PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Arvind Chandrasekaran	08/13/2009
Brian M. Henderson	08/13/2009

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12547520

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CORRESPONDENCE DATA

Fax Number: (858)658-2502
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 858-658-5787
Email: Patent.Docketing.US@qualcomm.com
Correspondent Name: QUALCOMM Incorporated
Address Line 1: 5775 Morehouse Drive
Address Line 2: Patent Department
Address Line 4: San Diego, CALIFORNIA 92121-1714

ATTORNEY DOCKET NUMBER:	091905
NAME OF SUBMITTER:	Nicholas J. Pauley

Total Attachments: 3
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ASSIGNMENT

TO WHOM IT MAY CONCERN:

For the sum of One Dollar and other valuable consideration to us in hand paid, receipt of which is hereby acknowledged, be it known that We/I,

Arvind Chandrasekaran, a citizen of IN, having a mailing address of 5775 Morehouse Drive, San Diego, California and a resident of San Diego, California

Brian M. Henderson, a citizen of United States, having a mailing address of 5775 Morehouse Drive, San Diego, California and a resident of San Diego, California

have sold, assigned and transferred and by these presents do sell, assign, transfer and set over unto QUALCOMM Incorporated, a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, its successors, legal representatives, or assigns, the entire right, title and interest in and to a certain invention relating to **Semiconductor Wafer-To-Wafer Bonding For Dissimilar Semiconductor Dies And/Or Wafers** by me devised and the application for United States Patent therefore filed in the United States Patent and Trademark Office on August 26, 2009, and assigned Serial No. 12/547,520, (and I hereby authorize and instruct **QUALCOMM Incorporated** to hereafter complete this Assignment by inserting the serial number and date in the space provided above when known), and all original and reissue patents granted thereof, and all divisions, continuations and continuations-in-part thereof, including the subject matter of any and all claims which may be obtained in every such patent, and all foreign rights to said invention, and covenant that I have full right to do so, and agree that I will communicate to said corporation or its representatives all facts known to me respecting said invention, whenever requested, and testify in any legal proceedings, sign all lawful papers, make all rightful oaths and generally do

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everything possible to aid said corporation, its successors, assigns and nominees, to obtain and enforce proper patent protection for said invention in all countries.

The Commissioner of Patents and Trademarks is requested to issue the Letters Patent which may be granted for said invention or any part thereof unto said corporation in keeping with this Assignment.

Done at San Diego, California this 13 day of Aug, 2009.

Arvind Chandrasekaran

Done at San Diego, California this _____ day of _________, 2009.

Brian M. Henderson

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Done at San Diego, California this _____ day of _________, 2009.

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Arvind Chandrasekaran

Done at San Diego, California this 13 day of August, 2009.

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Brian M. Henderson